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CLAIMS

We claim:

- 1 1. An electronic package comprising:
2 an electronic component having a first surface electrically
3 mounted to a substrate and a second arcuate surface having a
4 contour such that the distance between the first surface and the
5 second arcuate surface is greatest substantially near the center
6 of the electronic component.
- 1 2. The electronic package of claim 1, wherein an element is
2 mounted to the second arcuate surface of the electronic
3 component.
- 1 3. The electronic package of claim 2, wherein the element is
2 mounted to the second arcuate surface of the electronic component
3 by an adhesive.
- 1 4. The electronic package of claim 3, wherein the adhesive is a
2 thermally conductive reflowable material.
- 1 5. The electronic package of claim 2, wherein the element
2 mounted to the second arcuate surface of the electronic component
3 is a cover plate.

1 6. The electronic package of claim 2, wherein the element
2 mounted to the second arcuate surface of the electronic component
3 is a heat sink.

1 7. The electronic package of claim 1, wherein the second arcuate
2 surface of the electronic component is contoured using a
3 profiling tool having a concave profiling surface.

1 8. The electronic package of claim 1, wherein the second arcuate
2 surface of the electronic component has a domed shape.

1 9. The electronic package of claim 1, wherein the electronic
2 component has at least one profiled edge.

1 10. A method of forming an electronic package, comprising the
2 steps of:
3 providing an electronic component having a first featurized
4 surface and a second surface; and
5 removing a portion of the second surface such that the
6 second surface is substantially arcuate, having a thickness
7 greatest substantially near the center of the electronic
8 component.

1 11. The method of claim 10, further comprising the steps of:
2 electrically mounting the first featurized surface of the
3 electronic component to a substrate; and
4 mounting an element to the second surface of the electronic
5 component.

1 12. The method of claim 10, further comprising the step of:
2 removing at least one edge from a portion of the electronic
3 component.

1 13. The method of claim 11, wherein the substrate is a carrier.

1 14. The method of claim 11, wherein the element is a cover
2 plate.

- 1 15. The method of claim 11, wherein the element is a heat sink.
- 1 16. The method of claim 11, wherein the element is mounted to
2 the second surface of the electronic component using an adhesive.
- 1 17. The method of claim 16, wherein the adhesive is a thermally
2 conductive reflowable material.
- 1 18. The method of claim 10, wherein the step of removing a
2 portion of the second surface is performed using a profiling
3 tool.
- 1 19. The method of claim 18, wherein the profiling tool has a
2 concave profiling surface.
- 1 20. The method of claim 10, wherein the electronic device may
2 comprise an individual chip, a plurality of chips or a wafer.

1 21. A method of forming a chip, comprising the steps of:
2 providing an electronic component having a first featurized
3 surface and a second planar surface;
4 removing a first portion of the second planar surface
5 forming a first arcuate surface; and
6 removing a second portion of the second planar surface
7 forming a second arcuate surface.

1 22. The method of claim 21, further comprising the steps of:
2 profiling at least one edge of the electronic component.

1 23. A semiconductor chip having a substantially planar first
2 surface and an arcuate second surface.

1 24. The semiconductor chip of claim 23, wherein the
2 substantially planar first surface is electrically mounted to a
3 substrate, and the arcuate second surface is mounted to an
4 element.

1 25. The semiconductor chip of claim 24, wherein the arcuate
2 second surface is mounted to the element using a thermally
3 conductive reflowable adhesive.

1 26. The semiconductor chip of claim 24, wherein the element is a
2 cover plate.

1 27. The semiconductor chip of claim 24, wherein the element is a
2 heat sink.

1 28. The semiconductor chip of claim 23, wherein the distance
2 between the substantially planar first surface and the arcuate
3 second surface is greatest substantially near a center of the
4 chip.

1 29. The semiconductor chip of claim 23, wherein the
2 semiconductor chip has at least one profiled edge.

1 30. A method of forming an electronic package, comprising the
2 steps of:
3 providing an electronic component; and
4 profiling at least one edge of the component.

31. An electronic component having at least one substantially planar surface and at least one profiled edge.

1 32. An electronic package, comprising:
2 at least one electronic component, having at least one non-
3 planar surface.

1 33. The electronic package of claim 32, wherein the non-planar
2 surface is formed by profiling at least one surface of the
3 component.

1 34. The electronic package of claim 32, wherein the non-planar
2 surface is formed by profiling at least one edge of the
3 component.